METHOD FOR CORROSION PREVENTION DURING PLANARIZATION

ABSTRACT

The present invention relates to the reduction or complete prevention of Cu corrosion during a planarization or polishing process. In one aspect of the invention, RF signal is used to establish a negative bias in front of the wafer surface following polishing to eliminate Cu^{+} or Cu^{2+} migrations. In another aspect of the invention, a DC Voltage power supply is used to establish the negative bias.

Figure 1